Bond3D has developed a revolutionary printing technique to produce parts made from high performance polymers through additive manufacturing. The products have the same characteristics as products that are currently produced with conventional techniques. Since the foundation in 2014, Bond3D has been developing the 3D printer to put the innovative concepts into practice. The new generation of printers that are currently being developed can print the parts quickly, in high quality and reproducibly.

Does High Tech appeal to you? And an environment in which multidisciplinary insight is self-evident? Do you seize such a technical challenge with both hands and do you want to work with your colleagues to develop concepts for this? Take your chance now and get started with Bond3D and make an important contribution to the development of this revolutionary printer.

Internship heat conduction HPP

Bond3D is developing a 3D FDM printer for high performance polymers such as PEEK. The printer is designed for products in demanding medical and industrial applications. Key product features are 100% volume infill and isotropic high strength. Bond3D is participating in the EFRO project “Fast3D” for the continuous development of innovative 3D printing technology.

One of the project goals is to develop a high performance printing process for the use of filled HPP grades. An internship is available on the subject of filled high performance polymers (HPP), focussing on heat conducting material. Heat conducting HPP is used in applications where besides the unique properties of HPP heat conductivity is needed, such as heat exchangers or molds.

What are you going to do?

- Investigate the influence of filled HPP on printing behaviour
- Test the influence of filled HPP on mechanical behaviour
- Design optimization between strength and heat conductivity

What do we expect from you?

- You are studying a technical Master degree e.g. Mechanical Engineering, Physics, Aerospace Engineering, Applied mathematics
- English language fluency in speaking and writing;
- Affinity with programming (in e.g. python) and data analysis techniques
- Ability to work on a project independently
- Eager to gather in-depth knowledge about several aspects of additive manufacturing
- Perform practical research in combination with theoretical background

Does the above appeal to you? Then send your motivation letter and CV to: Bond3D for Arry Wegdam, via recruitment@bond3d.com